

ASIA-PACIFIC EMC WEEK

Technical Exhibition on EMC and RF/Microwave
Measurements & Instrumentation

2010 Asia-Pacific Symposium & Exhibition on Electromagnetic Compatibility in Beijing

Beijing International Conference Center, April 12-16, Beijing, China

The **2010 Asia-Pacific Electromagnetic Compatibility Symposium and Technical Exhibition** will be held in Beijing, Monday, April 12 through Friday, April 16, 2010.

After the resounding success of the 2008 APEMC in Singapore, it was decided to hold the 2010 Asia-Pacific EMC Symposium in Beijing. This event will continue in the spirit of APEMC and at the same time address the EMC community of the Asian-Pacific region and its link to the world. Beijing has been selected to host the 2010 APEMC because of its fabulous facilities and excellent business climate with the great success of the 2008 Beijing Olympic Game, and also because it is the world most vibrant city both in economic and technology development with rich cultures, modern & historical landmarks.

So come and join the EMC-Asia-Pacific Week in Beijing in 2010! We will offer a rich scientific program of highest quality with invited speakers from all over the world and provide a broad forum of exchange for both academia and industry alike.

The symposium will cover the entire scope of electromagnetic compatibility. Prospective authors are invited to submit original papers on their latest research results. We also solicit proposals for special sessions, industrial forum, workshops and tutorials.

Important Dates

Proposals for special/invited sessions and topical meetings / workshops and tutorials	Jul. 15, 2009
Preliminary paper submissions (4 pages in PDF format only)	Oct. 05, 2009
Notification of acceptance	Dec. 20, 2009
Final paper submission	Jan. 25, 2010

Details on the symposium websites: www.apemc2010.org
www.emc-zurich.org



Call for Papers

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Technical Topics

- **EMC Management**

Accreditation, certification, legislation, mutual recognition, EMC education, etc

- **EMC Measurement Techniques**

Sensor, instrumentation, testing facilities (reverberation / anechoic chamber, TEM, OATS), absorbing materials, measurement techniques, compliance testing

- **EMC Standards & Regulations**

- **EM Environment**

EM signal environment, UWB, impulse radar, Spectrum management, etc.

- **Lightning Protection**

- **Power System EMC and High Power EMC, IEMI**

- **System-Level EMC and Protection**

Shielding, filtering, coupling, grounding, PCB EMC, ESD

- **Transportation EMC**

Automotive EMC, Aerospace EMC, Naval EMC

- **Antenna and Wave Propagation**

Antenna design, sensors & probes, RFID

- **PCB & Electronic Packaging EMC and SI**

Interconnects, package & PCB substrate coupling

- **Semiconductor device and IC EMC**

IC, RFIC, RFID, sensor EMC modeling, design and measurement and ESD

- **Signal Integrity and Power Integrity**

- **Wireless Communication EMC**

Cellular device & systems, RF propagation, UWB, wireless LAN EMC, wireless regulations

- **Computational Electromagnetics**

Modeling techniques and applications

- **Bio-Medical Electromagnetics**

Biological effects, bio-electromagnetics, MRI, bio-sensing, bio-EM modeling

- **Nanotechnology for EMC**

Advanced materials, metamaterial, photonics

Paper Submission

Authors are requested to submit a preliminary paper up to 4 pages in length, including title, author's affiliation, abstract, figures and references.

One additional page should contain the paper title, author's affiliation, name of the correspondence author, his/her address, phone/fax numbers and e-mail address.

On the same page, you should clearly summarize the novelty of your contribution and indicate the desired technical areas (maximum of two). The submission must be in electronic format (PDF). A Word template is available on the symposium website. No hardcopies will be accepted.

Review

Submissions will be reviewed by the Technical Program Committee based on originality and novelty, quality, technical sophistication and depth and importance of topic.

APEMC Prizes

APEMC2010 Prizes consist of Best Paper Prize and Best Student Paper Prizes. Papers considered for the Student Paper Prize are expected to be predominantly the work of the student. Papers co-authored by a student and his advisor are eligible, provided the student is the principal author and also the presenter. Please indicate in your electronic submission if you want to be considered for the Student Paper Prize.

Accepted Papers

Notifications of paper acceptance and the necessary information to electronically submit the final version of the paper will be sent to the authors. Final papers shall be **four pages** including figures, tables and references.

Exhibition

The Technical Exhibition on EMC and RF/ Microwave Measurements and Instrumentation will be the major accompanying event of the Asia-Pacific EMC Week. The Technical Exhibition is a must-attend for all major manufacturers and distributors of EMC-related equipment and tools, such as: measurement and EMC test systems, protecting devices and components, RF/microwave instrumentation, electromagnetic analysis/synthesis software, etc.

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